

Device Specification



ELECTRICAL CHARACTERISTICS

Part Number	I _{hold} (A)	I _{trip} (A)	V _{max} (Vdc)	I _{max} (A)	P _d ^{max.} (W)	Maximum Time To Trip		Resistance	
						Current (A)	Time (Sec.)	R _{min} (Ω)	R _{1max} (Ω)
SMD1812P200TF	2.00	3.50	8	100	0.8	8.00	2.00	0.020	0.060

Note: I_{hold} = Hold current: maximum current device will pass without tripping in 20°C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 20°C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

P_d = Power dissipated from device when in the tripped state at 20°C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{1max} = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

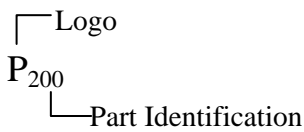
*Value specified were determined using the PCB with 0.030" * 1.5oz copper traces.

*Customer should verify the device performance in their specified conditions.

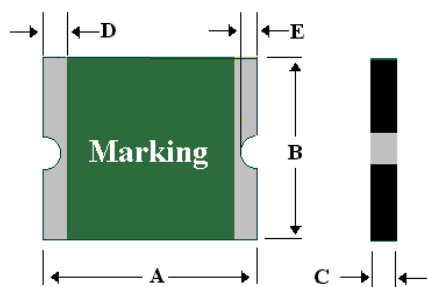
Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

Recognitions: 

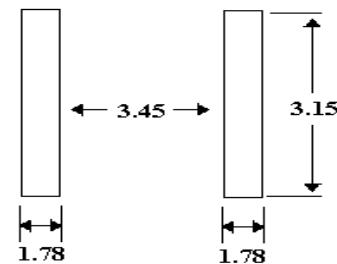
Marking:



FIGURE



SOLDER PAD LAYOUTS



Note: Polystar is Polytronics's manufacturing site in China. The Polystar ID marking shall appear on smallest package.

PHYSICAL DIMENSIONS (mm)

Part Number	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
SMD1812P200TF	4.37	4.73	3.07	3.41	0.81	1.20	0.30	1.20	0.25	0.50